	Hits	Search Text	DBs
1	1	("6641898").PN.	USPAT
2	0	6641898.URPN.	USPAT
3	8	("3947956" | "4795670" | "5744758" | "5879788" | "5977490" | "6207259" | "6440542" | "6459046").PN.	USPAT
4	3	"793405"	EPO; JPO; DERWENT; IBM_TDB
5	9	"1177901"	EPO; JPO; DERWENT; IBM_TDB
6	2	"11251703"	EPO; JPO; DERWENT; IBM_TDB
7	4	nakaya.in. and buffer and circuit adj board	USPAT; US-PGPUB
8	55	yasuhiro.in. and buffer and circuit adj board	USPAT; US-PGPUB
9	0	(yasuhiro.in. and buffer and circuit adj board) and intermetallic	USPAT; US-PGPUB
10	0	nakaya.in. and buffer and intermetallic	USPAT; US-PGPUB
11	1	yasuhiro.in. and buffer and intermetallic	USPAT; US-PGPUB
12	2	"11251751"	EPO; JPO; DERWENT; IBM_TDB
13	1	("6000129").PN.	USPAT
14	4	"576872"	EPO; JPO; DERWENT; IBM_TDB
15	20	(("6207259") or ("6440542") or ("5879788") or ("4795670") or ("5744758") or ("6459046") or ("3947956") or ("5977490") or ("4435611") or ("5031308") or ("5573622") or ("5906042") or ("5972482") or ("6000129") or ("5439164") or ("5551626") or ("5948533") or ("5746868") or ("4713494") or ("6143116")).PN.	USPAT
16	236979	(printed or wiring or circuit) adj board	EPO; JPO; DERWENT; IBM_TDB
17	162343	diffusion	EPO; JPO; DERWENT; IBM_TDB
18	1117689	via or viahole	EPO; JPO; DERWENT; IBM_TDB
19	81	((printed or wiring or circuit) adj board) and diffusion and (via or viahole)	EPO; JPO; DERWENT; IBM_TDB
20	24517	diffuse or diffuses	EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
21	9	((printed or wiring or circuit) adj board) and (via or viahole) and (diffuse or diffuses) not (((printed or wiring or circuit) adj board) and diffusion and (via or viahole))	EPO; JPO; DERWENT; IBM_TDB
22	172785	(printed or wiring or circuit) adj board	USPAT; US-PGPUB
23	217246	diffusion	USPAT; US-PGPUB
24	1471655	via or viahole	USPAT; US-PGPUB
25	5655	((printed or wiring or circuit) adj board) and diffusion and (via or viahole)	USPAT; US-PGPUB
26	21844	via adj hole or viahole	USPAT; US-PGPUB
27	78	((printed or wiring or circuit) adj board) and diffusion same (via adj hole or viahole)	USPAT; US-PGPUB
28	629	((printed or wiring or circuit) adj board) and diffusion and (via adj hole or viahole)	USPAT; US-PGPUB
29	78	((printed or wiring or circuit) adj board) and diffusion same (via adj hole or viahole)	USPAT; US-PGPUB
30	3	"793405"	EPO; JPO; DERWENT; IBM_TDB
31	1007	156/308.2.ccls.	USPAT; US-PGPUB
32	173020	(printed or wiring or circuit) adj board	USPAT; US-PGPUB
33	3723	428/209,901.ccls.	USPAT; US-PGPUB
34	5152	174/257-265.ccls.	USPAT; US-PGPUB
35	4891	((printed or wiring or circuit) adj board) and (156/308.2.ccls. or 428/209,901.ccls. or 174/257-265.ccls.)	USPAT; US-PGPUB
36	1635991	via or viahole or through adj hole	USPAT; US-PGPUB
37	3512	(((printed or wiring or circuit) adj board) and (156/308.2.ccls. or 428/209,901.ccls. or 174/257-265.ccls.)) and (via or viahole or through adj hole)	USPAT; US-PGPUB
38	217479	diffusion	USPAT; US-PGPUB

	Hits	Search Text	DBs
39	222	((((printed or wiring or circuit) adj board) and (156/308.2.ccls. or 428/209,901.ccls. or 174/257-265.ccls.)) and (via or viahole or through adj hole)) and diffusion	USPAT; US-PGPUB
40	4049138	tin or Sn or indium or In or Nickel or Ni or zind or Zn or aluminum or Al	USPAT; US-PGPUB
41	222	(((((printed or wiring or circuit) adj board) and (156/308.2.ccls. or 428/209,901.ccls. or 174/257-265.ccls.)) and (via or viahole or through adj hole)) and diffusion) and (tin or Sn or indium or In or Nickel or Ni or zind or Zn or aluminum or Al)	USPAT; US-PGPUB
42	2195	427/96,123,125,376.1.ccls.	USPAT; US-PGPUB
43	173355	(printed or wiring or circuit) adj board	USPAT; US-PGPUB
44	1639076	via or viahole or through adj hole	USPAT; US-PGPUB
45	124	427/96,123,125,376.1.ccls. and ((printed or wiring or circuit) adj board) and (via or viahole or through adj hole)	USPAT; US-PGPUB
46	217842	diffusion	USPAT; US-PGPUB
47	20	(427/96,123,125,376.1.ccls. and ((printed or wiring or circuit) adj board) and (via or viahole or through adj hole)) and diffusion	USPAT; US-PGPUB